# **74AUP2G57**

# Low-power dual PCB configurable multiple function gate Rev. 4 — 17 July 2023 Product data sheet

### 1. General description

The 74AUP2G57 is a dual configurable multiple function gate with Schmitt-trigger inputs. Each gate within the device can be configured as any of the following logic functions AND, OR, NAND, NOR, XNOR, inverter and buffer; using the 3-bit input. All inputs can be connected directly to  $V_{CC}$  or GND.

This device ensures very low static and dynamic power consumption across the entire  $V_{CC}$  range from 0.8 V to 3.6 V.

This device is fully specified for partial power down applications using  $I_{OFF}$ . The  $I_{OFF}$  circuitry disables the output, preventing the potentially damaging backflow current through the device when it is powered down.

#### 2. Features and benefits

- Wide supply voltage range from 0.8 V to 3.6 V
- · High noise immunity
- Low static power consumption; I<sub>CC</sub> = 0.9 μA (maximum)
- Latch-up performance exceeds 100 mA per JESD 78 Class II
- Inputs accept voltages up to 3.6 V
- Low noise overshoot and undershoot < 10% of V<sub>CC</sub>
- I<sub>OFF</sub> circuitry provides partial power-down mode operation
- · ESD protection:
  - HBM: ANSI/ESDA/JEDEC JS-001 class 3A exceeds 5000 V
  - CDM: ANSI/ESDA/JEDEC JS-002 class C3 exceeds 1000 V
- Specified from -40 °C to +85 °C and -40 °C to +125 °C

# 3. Ordering information

#### **Table 1. Ordering information**

Type number	Package								
	Temperature range	Name	Description	Version					
74AUP2G57DP	-40 °C to +125 °C	TSSOP10	plastic thin shrink small outline package; 10 leads; body width 3 mm	SOT552-1					
74AUP2G57GU	-40 °C to +125 °C	XQFN10	plastic, extremely thin quad flat package; no leads; 10 terminals; body 1.40 × 1.80 × 0.50 mm	SOT1160-1					

# 4. Marking

#### Table 2. Marking

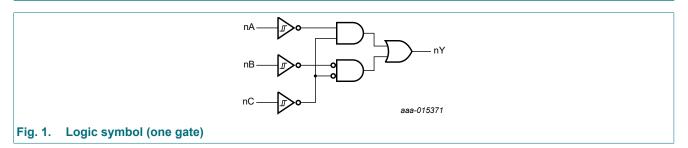
14010 21 11141 1119	
Type number	Marking code [1]
74AUP2G57DP	aC
74AUP2G57GU	aC

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.



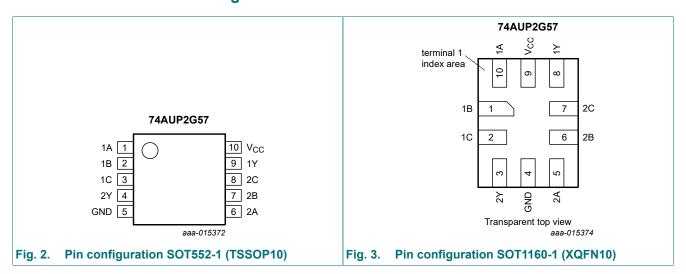
### Low-power dual PCB configurable multiple function gate

# 5. Functional diagram



# 6. Pinning information

### 6.1. Pinning



### 6.2. Pin description

Table 3. Pin description

Symbol	Pin	Pin		
	SOT552-1	SOT1160-1		
1A, 2A	1, 6	10, 5	data input	
1B, 2B	2, 7	1, 6	data input	
1C, 2C	3, 8	2, 7	data input	
1Y, 2Y	9, 4	8, 3	data output	
GND	5	4	ground (0 V)	
V <sub>CC</sub>	10	9	supply voltage	

### Low-power dual PCB configurable multiple function gate

# 7. Functional description

#### **Table 4. Function table**

 $H = HIGH \ voltage \ level; \ L = LOW \ voltage \ level.$ 

Input			Output
nC	nB	nA	nY
L	L	L	Н
L	L	Н	L
L	Н	L	Н
L	Н	Н	L
Н	L	L	L
Н	L	Н	L
Н	Н	L	Н
Н	Н	Н	Н

# 7.1. Logic configurations

**Table 5. Function selection table** 

Tuble 6. I diletion selection tuble						
Logic function	Figure					
2-input AND	see Fig. 4					
2-input AND with both inputs inverted	see Fig. 7					
2-input NAND with inverted input	see Fig. 5 and Fig. 6					
2-input OR with inverted input	see Fig. 5 and Fig. 6					
2-input NOR	see Fig. 7					
2-input NOR with both inputs inverted	see Fig. 4					
2-input XNOR	see Fig. 8					
Inverter	see Fig. 9					
Buffer	see Fig. 10					

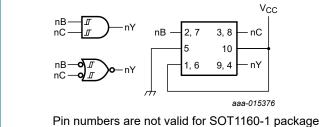
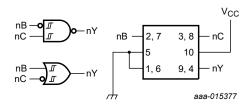


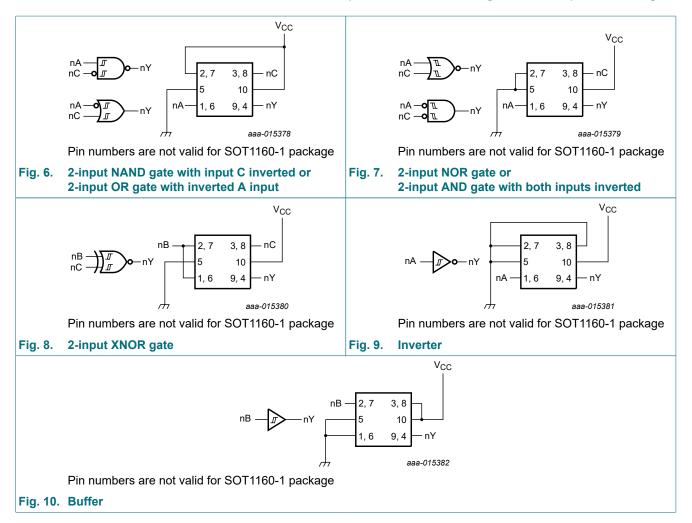
Fig. 4. 2-input AND gate or 2-input NOR gate with both inputs inverted



Pin numbers are not valid for SOT1160-1 package

Fig. 5. 2-input NAND gate with input B inverted or 2-input OR gate with inverted C input

#### Low-power dual PCB configurable multiple function gate



# 8. Limiting values

#### Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		Min	Max	Unit
V <sub>CC</sub>	supply voltage			-0.5	+4.6	V
I <sub>IK</sub>	input clamping current	V <sub>I</sub> < 0 V		-50	-	mA
VI	input voltage		[1]	-0.5	+4.6	V
I <sub>OK</sub>	output clamping current	V <sub>O</sub> < 0 V		-50	-	mA
Vo	output voltage	Active mode and Power-down mode	[1]	-0.5	+4.6	V
I <sub>O</sub>	output current	V <sub>O</sub> = 0 V to V <sub>CC</sub>		-	±20	mA
I <sub>CC</sub>	supply current			-	50	mA
$I_{GND}$	ground current			-50	-	mA
T <sub>stg</sub>	storage temperature			-65	+150	°C
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = -40 °C to +125 °C	[2]	-	250	mW

<sup>[1]</sup> The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>[2]</sup> For SOT552-1 (TSSOP10) packages: P<sub>tot</sub> derates linearly with 8.3 mW/K above 120 °C. For SOT1160-1 (XQFN10) package: P<sub>tot</sub> derates linearly with 7.1 mW/K above 115 °C.

### Low-power dual PCB configurable multiple function gate

# 9. Recommended operating conditions

Table 7. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		0.8	3.6	V
VI	input voltage		0	3.6	V
Vo	output voltage	Active mode	0	V <sub>CC</sub>	V
		Power-down mode; V <sub>CC</sub> = 0 V	0	3.6	V
T <sub>amb</sub>	ambient temperature		-40	+125	°C

### 10. Static characteristics

#### **Table 8. Static characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
T <sub>amb</sub> = 2	5 °C	= V <sub>T+</sub> or V <sub>T</sub> .  I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 0.8 V to 3.6 V  I <sub>O</sub> = -1.1 mA; V <sub>CC</sub> = 1.1 V  I <sub>O</sub> = -1.7 mA; V <sub>CC</sub> = 1.65 V  I <sub>O</sub> = -2.3 mA; V <sub>CC</sub> = 2.3 V  I <sub>O</sub> = -2.7 mA; V <sub>CC</sub> = 3.0 V  I <sub>O</sub> = -2.7 mA; V <sub>CC</sub> = 3.0 V  I <sub>O</sub> = -2.7 mA; V <sub>CC</sub> = 1.4 V  I <sub>O</sub> = -2.3 mA; V <sub>CC</sub> = 3.0 V  I <sub>O</sub> = -2.3 mA; V <sub>CC</sub> = 3.0 V  I <sub>O</sub> = -2.7 mA; V <sub>CC</sub> = 3.0 V  I <sub>O</sub> = -2.7 mA; V <sub>CC</sub> = 3.0 V  I <sub>O</sub> = -2.7 mA; V <sub>CC</sub> = 3.0 V  I <sub>O</sub> = -2.7 mA; V <sub>CC</sub> = 3.0 V  I <sub>O</sub> = 2.3 μA; V <sub>CC</sub> = 0.8 V to 3.6 V  I <sub>O</sub> = 1.1 mA; V <sub>CC</sub> = 1.1 V  I <sub>O</sub> = 1.1 mA; V <sub>CC</sub> = 1.4 V  I <sub>O</sub> = 1.9 mA; V <sub>CC</sub> = 1.65 V  I <sub>O</sub> = 1.9 mA; V <sub>CC</sub> = 3.0 V  I <sub>O</sub> = 2.3 mA; V <sub>CC</sub> = 3.0 V  I <sub>O</sub> = 2.3 mA; V <sub>CC</sub> = 3.0 V  I <sub>O</sub> = 1.9 mA; V <sub>CC</sub> = 3.0 V  I <sub>O</sub> = 2.3 mA; V <sub>CC</sub> = 3.0 V  I <sub>O</sub> = 2.7 mA; V <sub>CC</sub> = 3.0 V  I <sub>O</sub> = 3.1 mA; V <sub>CC</sub> = 3.0 V  I <sub>O</sub> = 2.7 mA; V <sub>CC</sub> = 3.0 V  I <sub>O</sub> = 2.7 mA; V <sub>CC</sub> = 3.0 V  I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 3.0 V  I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 3.0 V  I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 3.0 V  I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 3.0 V  I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 3.0 V  I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 3.0 V  I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 3.0 V  I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 3.0 V  I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 0 V to 3.6 V  I <sub>O</sub> = 6ND to 3.6 V; V <sub>CC</sub> = 0 V to 0.2 V  I <sub>O</sub> = 6ND or V <sub>CC</sub> ; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 0 V to 0.2 V  I <sub>O</sub> = 6ND or V <sub>CC</sub> ; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 0.8 V to 3.6 V  I <sub>O</sub> = 6ND or V <sub>CC</sub> ; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 0.8 V to 3.6 V  I <sub>O</sub> = 6ND or V <sub>CC</sub> ; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 0.8 V to 3.6 V  I <sub>O</sub> = 6ND or V <sub>CC</sub> ; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 0.8 V to 3.6 V				
V <sub>OH</sub>	HIGH-level output	$V_I = V_{T+}$ or $V_{T-}$				
	voltage	I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 0.8 V to 3.6 V	V <sub>CC</sub> - 0.1	-	-	V
		I <sub>O</sub> = -1.1 mA; V <sub>CC</sub> = 1.1 V	0.75 × V <sub>CC</sub>	-	-	V
		I <sub>O</sub> = -1.7 mA; V <sub>CC</sub> = 1.4 V	1.11	-	-	V
		I <sub>O</sub> = -1.9 mA; V <sub>CC</sub> = 1.65 V	1.32	-	-	V
		I <sub>O</sub> = -2.3 mA; V <sub>CC</sub> = 2.3 V	2.05	-	-	V
		I <sub>O</sub> = -3.1 mA; V <sub>CC</sub> = 2.3 V	1.9	-	-	V
		I <sub>O</sub> = -2.7 mA; V <sub>CC</sub> = 3.0 V	2.72	-	-	V
		I <sub>O</sub> = -4.0 mA; V <sub>CC</sub> = 3.0 V	2.6	-	-	V
$V_{OL}$	LOW-level output	$V_I = V_{T+}$ or $V_{T-}$				
	voltage	$I_{O}$ = 20 $\mu$ A; $V_{CC}$ = 0.8 V to 3.6 V	-	-	0.1	V
		I <sub>O</sub> = 1.1 mA; V <sub>CC</sub> = 1.1 V	-	-	0.3 × V <sub>CC</sub>	V
		I <sub>O</sub> = 1.7 mA; V <sub>CC</sub> = 1.4 V	-	-	0.31	V
		I <sub>O</sub> = 1.9 mA; V <sub>CC</sub> = 1.65 V	-	-	0.31	V
		$I_O = 2.3 \text{ mA}; V_{CC} = 2.3 \text{ V}$	-	-	0.31	V
		I <sub>O</sub> = 3.1 mA; V <sub>CC</sub> = 2.3 V	-	-	0.44	V
		I <sub>O</sub> = 2.7 mA; V <sub>CC</sub> = 3.0 V	-	-	0.31	V
		I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 3.0 V	-	-	0.44	V
I <sub>I</sub>	input leakage current	$V_I = GND \text{ to } 3.6 \text{ V}; V_{CC} = 0 \text{ V to } 3.6 \text{ V}$	-	-	±0.1	μA
I <sub>OFF</sub>	power-off leakage current	$V_1$ or $V_0 = 0$ V to 3.6 V; $V_{CC} = 0$ V	-	-	±0.2	μA
Δl <sub>OFF</sub>	additional power-off leakage current	$V_{I}$ or $V_{O} = 0$ V to 3.6 V; $V_{CC} = 0$ V to 0.2 V	-	-	±0.2	μA
I <sub>CC</sub>	supply current	$V_I$ = GND or $V_{CC}$ ; $I_O$ = 0 A; $V_{CC}$ = 0.8 V to 3.6 V	-	-	0.5	μΑ
ΔI <sub>CC</sub>	additional supply current	$V_1 = V_{CC} - 0.6 \text{ V}; I_0 = 0 \text{ A}; V_{CC} = 3.3 \text{ V}$	-	-	40	μA
Cı	input capacitance	$V_I$ = GND or $V_{CC}$ ; $V_{CC}$ = 0 V to 3.6 V	-	1.1	-	рF
Co	output capacitance	$V_O = GND; V_{CC} = 0 V$	-	1.7	-	pF

# Low-power dual PCB configurable multiple function gate

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
T <sub>amb</sub> = -	40 °C to +85 °C					•
V <sub>OH</sub>	HIGH-level output	$V_I = V_{T+}$ or $V_{T-}$				
	voltage	$I_{O}$ = -20 $\mu$ A; $V_{CC}$ = 0.8 V to 3.6 V	V <sub>CC</sub> - 0.1	-	-	V
		I <sub>O</sub> = -1.1 mA; V <sub>CC</sub> = 1.1 V	0.7 × V <sub>CC</sub>	-	-	V
		I <sub>O</sub> = -1.7 mA; V <sub>CC</sub> = 1.4 V	1.03	-	-	V
		I <sub>O</sub> = -1.9 mA; V <sub>CC</sub> = 1.65 V	1.30	-	-	V
		I <sub>O</sub> = -2.3 mA; V <sub>CC</sub> = 2.3 V	1.97	-	-	V
		I <sub>O</sub> = -3.1 mA; V <sub>CC</sub> = 2.3 V	1.85	-	-	V
		I <sub>O</sub> = -2.7 mA; V <sub>CC</sub> = 3.0 V	2.67	-	-	V
		I <sub>O</sub> = -4.0 mA; V <sub>CC</sub> = 3.0 V	2.55	-	-	V
V <sub>OL</sub>	LOW-level output voltage	$V_I = V_{T+}$ or $V_{T-}$				
		$I_{O}$ = 20 $\mu$ A; $V_{CC}$ = 0.8 V to 3.6 V	-	-	0.1	V
		I <sub>O</sub> = 1.1 mA; V <sub>CC</sub> = 1.1 V	-	-	0.3 × V <sub>CC</sub>	V
		I <sub>O</sub> = 1.7 mA; V <sub>CC</sub> = 1.4 V	-	-	0.37	V
		I <sub>O</sub> = 1.9 mA; V <sub>CC</sub> = 1.65 V	-	-	0.35	V
		I <sub>O</sub> = 2.3 mA; V <sub>CC</sub> = 2.3 V	-	-	0.33	V
		I <sub>O</sub> = 3.1 mA; V <sub>CC</sub> = 2.3 V	-	-	0.45	V
		I <sub>O</sub> = 2.7 mA; V <sub>CC</sub> = 3.0 V	-	-	0.33	V
		I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 3.0 V	-	-	0.45	V
I <sub>I</sub>	input leakage current	$V_I = GND \text{ to } 3.6 \text{ V}; V_{CC} = 0 \text{ V to } 3.6 \text{ V}$	-	-	±0.5	μA
I <sub>OFF</sub>	power-off leakage current	$V_1$ or $V_0 = 0$ V to 3.6 V; $V_{CC} = 0$ V	-	-	±0.5	μΑ
ΔI <sub>OFF</sub>	additional power-off leakage current	$V_{I}$ or $V_{O} = 0$ V to 3.6 V; $V_{CC} = 0$ V to 0.2 V	-	-	±0.6	μA
I <sub>CC</sub>	supply current	$V_{I}$ = GND or $V_{CC}$ ; $I_{O}$ = 0 A; $V_{CC}$ = 0.8 V to 3.6 V	-	-	0.9	μA
ΔI <sub>CC</sub>	additional supply current	$V_I = V_{CC} - 0.6 \text{ V}; I_O = 0 \text{ A}; V_{CC} = 3.3 \text{ V}$	-	-	50	μA

### Low-power dual PCB configurable multiple function gate

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
T <sub>amb</sub> = -4	40 °C to +125 °C					
V <sub>OH</sub>	HIGH-level output	$V_I = V_{T+}$ or $V_{T-}$				
	voltage	$I_{O}$ = -20 $\mu$ A; $V_{CC}$ = 0.8 V to 3.6 V	V <sub>CC</sub> - 0.11	-	-	V
		I <sub>O</sub> = -1.1 mA; V <sub>CC</sub> = 1.1 V	0.6 × V <sub>CC</sub>	-	-	V
		I <sub>O</sub> = -1.7 mA; V <sub>CC</sub> = 1.4 V	0.93	-	-	V
		I <sub>O</sub> = -1.9 mA; V <sub>CC</sub> = 1.65 V	1.17	-	-	V
		I <sub>O</sub> = -2.3 mA; V <sub>CC</sub> = 2.3 V	1.77	-	-	V
		I <sub>O</sub> = -3.1 mA; V <sub>CC</sub> = 2.3 V	1.67	-	-	V
		I <sub>O</sub> = -2.7 mA; V <sub>CC</sub> = 3.0 V	2.40	-	-	V
		I <sub>O</sub> = -4.0 mA; V <sub>CC</sub> = 3.0 V	2.30	-	-	V
V <sub>OL</sub>	LOW-level output	$V_I = V_{T+}$ or $V_{T-}$				
	voltage	$I_{O}$ = 20 $\mu$ A; $V_{CC}$ = 0.8 V to 3.6 V	-	-	0.11	V
		I <sub>O</sub> = 1.1 mA; V <sub>CC</sub> = 1.1 V	-	-	0.33 × V <sub>CC</sub>	V
		I <sub>O</sub> = 1.7 mA; V <sub>CC</sub> = 1.4 V	-	-	0.41	V
		I <sub>O</sub> = 1.9 mA; V <sub>CC</sub> = 1.65 V	-	-	0.39	V
		I <sub>O</sub> = 2.3 mA; V <sub>CC</sub> = 2.3 V	-	-	0.36	V
		I <sub>O</sub> = 3.1 mA; V <sub>CC</sub> = 2.3 V	-	-	0.50	V
		I <sub>O</sub> = 2.7 mA; V <sub>CC</sub> = 3.0 V	-	-	0.36	V
		I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 3.0 V	-	-	0.50	V
l <sub>l</sub>	input leakage current	$V_{I}$ = GND to 3.6 V; $V_{CC}$ = 0 V to 3.6 V	-	-	±0.75	μΑ
I <sub>OFF</sub>	power-off leakage current	$V_{I}$ or $V_{O} = 0$ V to 3.6 V; $V_{CC} = 0$ V	-	-	±0.75	μΑ
ΔI <sub>OFF</sub>	additional power-off leakage current	$V_1$ or $V_0 = 0$ V to 3.6 V; $V_{CC} = 0$ V to 0.2 V	-	-	±0.75	μΑ
I <sub>CC</sub>	supply current	$V_{I}$ = GND or $V_{CC}$ ; $I_{O}$ = 0 A; $V_{CC}$ = 0.8 V to 3.6 V	-	-	1.4	μA
Δl <sub>CC</sub>	additional supply current	$V_I = V_{CC} - 0.6 \text{ V}; I_O = 0 \text{ A}; V_{CC} = 3.3 \text{ V}$	-	-	75	μA

# 11. Dynamic characteristics

### **Table 9. Dynamic characteristics**

Voltages are referenced to GND (ground = 0 V); for test circuit, see Fig. 12.

Symbol	Parameter	Conditions		25 °C			C to	-40 ° +12		Unit					
			ı	Min	Typ [1]	Max	Min	Max	Min	Max					
C <sub>L</sub> = 5 p	F														
t <sub>pd</sub> prop	propagation	nA, nB and nC to nY; see Fig. 11	[2]												
	delay	delay	delay	delay	delay	V <sub>CC</sub> = 0.8 V		-	22.6	-	-	-	-	-	ns
		V <sub>CC</sub> = 1.1 V to 1.3 V	:	2.8	6.5	12.6	2.5	13.0	2.5	13.2	ns				
		V <sub>CC</sub> = 1.4 V to 1.6 V	:	2.2	4.6	7.6	2.5	8.2	2.5	8.6	ns				
		V <sub>CC</sub> = 1.65 V to 1.95 V	:	2.1	3.9	6.2	2.0	6.8	2.0	7.2	ns				
		V <sub>CC</sub> = 2.3 V to 2.7 V	:	2.0	3.1	4.5	1.8	5.1	1.8	5.3	ns				
		V <sub>CC</sub> = 3.0 V to 3.6 V		1.8	2.8	3.9	1.5	4.1	1.5	4.3	ns				

### Low-power dual PCB configurable multiple function gate

Symbol	Parameter	Conditions	25 °C			°C to 5 °C		°C to 5 °C	Unit	
			Min	Typ [1]	Max	Min	Max	Min	Max	
C <sub>L</sub> = 10	pF									
t <sub>pd</sub>	propagation	nA, nB and nC to nY; see Fig. 11 [2]								
	delay	V <sub>CC</sub> = 0.8 V	-	26.1	-	-	-	-	-	ns
		V <sub>CC</sub> = 1.1 V to 1.3 V	3.2	7.3	14.4	2.8	14.9	2.8	15.2	ns
		V <sub>CC</sub> = 1.4 V to 1.6 V	2.6	5.2	8.7	2.8	9.3	2.8	9.8	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	2.5	4.5	7.0	2.2	7.8	2.2	8.2	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	2.4	3.7	5.2	2.1	5.9	2.1	6.2	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	2.3	3.4	4.6	1.9	4.9	1.9	5.1	ns
C <sub>L</sub> = 15	pF			•						
t <sub>pd</sub>	propagation	nA, nB and nC to nY; see Fig. 11 [2]								
	delay	V <sub>CC</sub> = 0.8 V	-	31.6	-	-	-	-	-	ns
		V <sub>CC</sub> = 1.1 V to 1.3 V	3.4	8.0	15.7	3.1	16.7	3.1	17.0	ns
		V <sub>CC</sub> = 1.4 V to 1.6 V	2.8	5.7	9.4	3.1	10.4	3.1	10.9	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	2.6	4.9	7.7	2.5	8.7	2.5	9.2	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	2.6	4.1	5.7	2.4	6.5	2.4	6.9	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	2.5	3.8	5.0	2.2	5.5	2.2	5.7	ns
C <sub>L</sub> = 30	pF									
t <sub>pd</sub>	propagation	nA, nB and nC to nY; see Fig. 11 [2]								
·	delay	V <sub>CC</sub> = 0.8 V	-	37.8	-	-	-	-	-	ns
		V <sub>CC</sub> = 1.1 V to 1.3 V	4.6	10.4	20.9	3.9	21.8	3.9	22.3	ns
		V <sub>CC</sub> = 1.4 V to 1.6 V	3.6	7.4	12.2	3.8	13.4	3.8	14.1	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	3.5	6.2	9.9	3.1	11.1	3.1	11.8	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	3.4	5.2	7.4	3.1	8.3	3.1	8.8	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	3.2	4.9	6.6	2.8	7.0	2.8	7.4	ns
C <sub>L</sub> = 5 p	F, 10 pF, 15 pF	and 30 pF								
C <sub>PD</sub>	power	$f_i = 1 \text{ MHz}; V_I = \text{GND to } V_{CC}$ [3] [4]								
	dissipation	V <sub>CC</sub> = 0.8 V	-	2.6	-	-	-	-	-	pF
	capacitance	V <sub>CC</sub> = 1.1 V to 1.3 V	-	2.8	-	-	-	-	-	pF
		V <sub>CC</sub> = 1.4 V to 1.6 V	-	2.9	-	-	-	-	-	pF
		V <sub>CC</sub> = 1.65 V to 1.95 V	-	3.1	-	-	-	-	-	pF
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	3.7	-	-	-	-	-	pF
		V <sub>CC</sub> = 3.0 V to 3.6 V	_	4.3	-	-	-	-	_	pF

All typical values are measured at nominal V<sub>CC</sub>.

 $f_i$  = input frequency in MHz;

f<sub>o</sub> = output frequency in MHz;

C<sub>L</sub> = output load capacitance in pF;

V<sub>CC</sub> = supply voltage in V;

N = number of inputs switching;  $\Sigma (C_L \times V_{CC}^{\ 2} \times f_o) = \text{sum of the outputs}.$ 

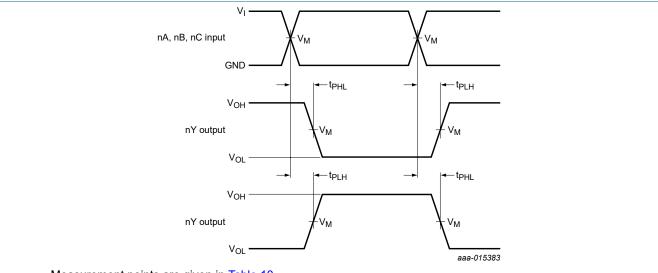
<sup>[1]</sup> [2]

 $t_{pd}$  is the same as  $t_{PLH}$  and  $t_{PHL}$ . All specified values are the average typical values over all stated loads.

<sup>[4]</sup>  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu$ W).  $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma (C_L \times V_{CC}^2 \times f_o)$  where:

#### Low-power dual PCB configurable multiple function gate

#### 11.1. Waveform and test circuit



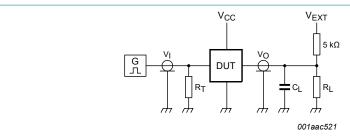
Measurement points are given in Table 10.

 $V_{\text{OL}}$  and  $V_{\text{OH}}$  are typical output voltage levels that occur with the output load.

Fig. 11. Input nA, nB and nC to output nY propagation delay times

Table 10. Measurement points

Supply voltage	Output	Input		
V <sub>CC</sub>	V <sub>M</sub>	V <sub>M</sub>	VI	$t_r = t_f$
0.8 V to 3.6 V	0.5 × V <sub>CC</sub>	0.5 × V <sub>CC</sub>	V <sub>CC</sub>	≤ 3.0 ns



Test data is given in Table 11.

Definitions for test circuit:

R<sub>L</sub> = Load resistance.

C<sub>L</sub> = Load capacitance including jig and probe capacitance.

 $R_T$  = Termination resistance should be equal to the output impedance  $Z_o$  of the pulse generator.

 $V_{EXT}$  = External voltage for measuring switching times.

Fig. 12. Test circuit for measuring switching times

Table 11. Test data

Supply voltage	Load		V <sub>EXT</sub>				
V <sub>CC</sub>	CL	R <sub>L</sub> [1]	t <sub>PLH</sub> , t <sub>PHL</sub>	t <sub>PZH</sub> , t <sub>PHZ</sub>	t <sub>PZL</sub> , t <sub>PLZ</sub>		
0.8 V to 3.6 V	5 pF, 10 pF, 15 pF and 30 pF	5 kΩ or 1 MΩ	open	GND	2 × V <sub>CC</sub>		

[1] For measuring enable and disable times,  $R_L$  = 5  $k\Omega.$ 

For measuring propagation delays, set-up and hold times, and pulse width,  $R_{L}$  = 1  $\mbox{M}\Omega.$ 

### Low-power dual PCB configurable multiple function gate

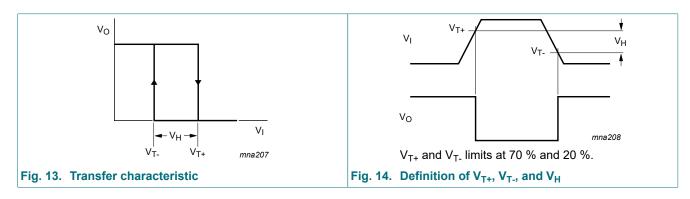
# 12. Transfer characteristics

#### **Table 12. Transfer characteristics**

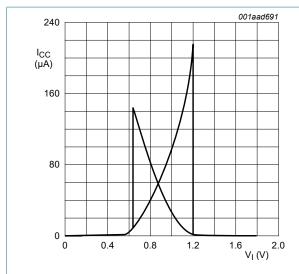
Voltages are referenced to GND (ground = 0 V); for test circuit see Fig. 12.

Symbol	Parameter	Conditions		25 °C		-40 °C to	o +85 °C	-40 °C to	+125 °C	Unit
			Min	Тур	Max	Min	Max	Min	Max	
$V_{T+}$	positive-going	see <u>Fig. 13</u> and <u>Fig. 14</u>								
	threshold voltage	V <sub>CC</sub> = 0.8 V	0.30	-	0.60	0.30	0.60	0.30	0.62	V
		V <sub>CC</sub> = 1.1 V	0.53	-	0.90	0.53	0.90	0.53	0.92	V
		V <sub>CC</sub> = 1.4 V	0.74	-	1.11	0.74	1.11	0.74	1.13	V
		V <sub>CC</sub> = 1.65 V	0.91	-	1.29	0.91	1.29	0.91	1.31	V
		V <sub>CC</sub> = 2.3 V	1.37	-	1.77	1.37	1.77	1.37	1.80	V
		V <sub>CC</sub> = 3.0 V	1.88	-	2.29	1.88	2.29	1.88	2.32	V
V <sub>T-</sub>	/ <sub>T-</sub> negative-going	see Fig. 13 and Fig. 14								
	threshold voltage	V <sub>CC</sub> = 0.8 V	0.10	-	0.60	0.10	0.60	0.10	0.60	V
		V <sub>CC</sub> = 1.1 V	0.26	-	0.65	0.26	0.65	0.26	0.65	V
		V <sub>CC</sub> = 1.4 V	0.39	-	0.75	0.39	0.75	0.39	0.75	V
		V <sub>CC</sub> = 1.65 V	0.47	-	0.84	0.47	0.84	0.47	0.84	V
		V <sub>CC</sub> = 2.3 V	0.69	-	1.04	0.69	1.04	0.69	1.04	V
		V <sub>CC</sub> = 3.0 V	0.88	-	1.24	0.88	1.24	0.88	1.24	V
V <sub>H</sub>	hysteresis voltage	(V <sub>T+</sub> - V <sub>T-</sub> ); see <u>Fig. 13</u> , <u>Fig. 14</u> , <u>Fig. 15</u> and <u>Fig. 16</u>								
		V <sub>CC</sub> = 0.8 V	0.07	-	0.50	0.07	0.50	0.07	0.50	V
		V <sub>CC</sub> = 1.1 V	0.08	-	0.46	0.08	0.46	0.08	0.46	V
		V <sub>CC</sub> = 1.4 V	0.18	-	0.56	0.18	0.56	0.18	0.56	V
		V <sub>CC</sub> = 1.65 V	0.27	-	0.66	0.27	0.66	0.27	0.66	V
		V <sub>CC</sub> = 2.3 V	0.53	-	0.92	0.53	0.92	0.53	0.92	V
		V <sub>CC</sub> = 3.0 V	0.79	-	1.31	0.79	1.31	0.79	1.31	V

### 12.1. Waveform transfer characteristics



### Low-power dual PCB configurable multiple function gate



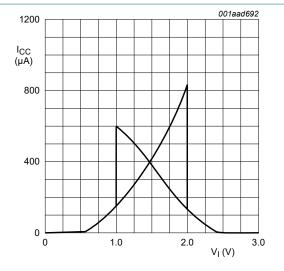


Fig. 15. Typical transfer characteristics;  $V_{CC} = 1.8 \text{ V}$ 

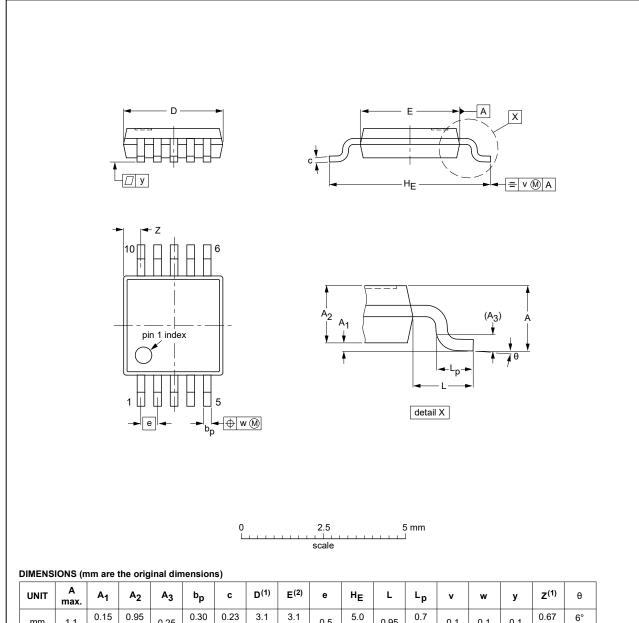
Fig. 16. Typical transfer characteristics;  $V_{CC} = 3.0 \text{ V}$ 

### Low-power dual PCB configurable multiple function gate

# 13. Package outline

#### TSSOP10: plastic thin shrink small outline package; 10 leads; body width 3 mm

SOT552-1



UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	А3	bp	С	D <sup>(1)</sup>	E <sup>(2)</sup>	е	HE	L	Lp	v	w	у	Z <sup>(1)</sup>	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.15	0.23 0.15	3.1 2.9	3.1 2.9	0.5	5.0 4.8	0.95	0.7 0.4	0.1	0.1	0.1	0.67 0.34	6° 0°

#### Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT552-1						<del>99-07-29</del> 03-02-18

Fig. 17. Package outline SOT552-1 (TSSOP10)

#### Low-power dual PCB configurable multiple function gate

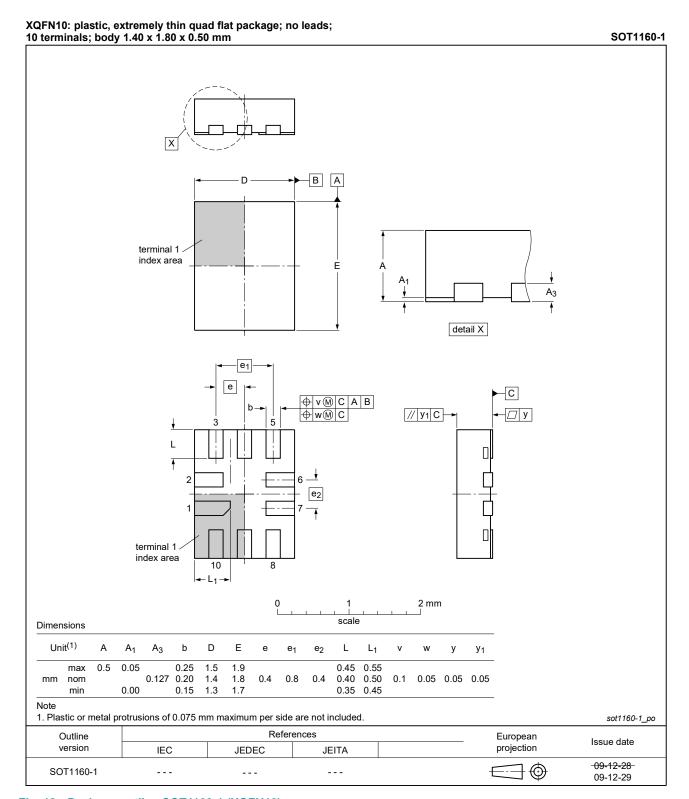


Fig. 18. Package outline SOT1160-1 (XQFN10)

### Low-power dual PCB configurable multiple function gate

# 14. Abbreviations

#### **Table 13. Abbreviations**

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
НВМ	Human Body Model
PCB	Printed Circuit Board

# 15. Revision history

#### **Table 14. Revision history**

Document ID	Release date	Data sheet status	Change notice	Supersedes				
74AUP2G57 v.4	20230717	Product data sheet	-	74AUP2G57 v.3				
Modifications:	Section 2: E	Section 2: ESD specification updated according to the latest JEDEC standard.						
74AUP2G57 v.3	20210507	Product data sheet	-	74AUP2G57 v.2				
Modifications:	guidelines of Legal texts Type number	<ul> <li>The format of this data sheet has been redesigned to comply with the identity guidelines of Nexperia.</li> <li>Legal texts have been adapted to the new company name where appropriate.</li> <li>Type number 74AUP2G57GF (SOT1081-2 / XSON10) removed.</li> <li>Section 8: Derating values for Ptot total power dissipation updated.</li> </ul>						
74AUP2G57 v.2	20151202	Product data sheet	-	74AUP2G57 v.1				
Modifications:	125 °C.	<ul> <li>Maximum value temperature range TSSOP10 (74AUP2G57DP) changed from 85 °C to 125 °C.</li> <li>Removed 74AUP2G57GM (SOT1049-3).</li> </ul>						
74AUP2G57 v.1	20141104	Product data sheet	-	-				

#### Low-power dual PCB configurable multiple function gate

### 16. Legal information

#### **Data sheet status**

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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### Low-power dual PCB configurable multiple function gate

# **Contents**

1. General description	1
2. Features and benefits	1
3. Ordering information	
4. Marking	
5. Functional diagram	2
6. Pinning information	
6.1. Pinning	
6.2. Pin description	
7. Functional description	
7.1. Logic configurations	
8. Limiting values	
9. Recommended operating conditions	
10. Static characteristics	
11. Dynamic characteristics	
11.1. Waveform and test circuit	
12. Transfer characteristics	
12.1. Waveform transfer characteristics	
13. Package outline	
14. Abbreviations	
15. Revision history	
16. Legal information	
10. Legai illioilliatioil	10

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